

IN THE CLAIMS:

Claims 31 through 94 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

Listing of Claims:

- SW
1/12/05
OK'd to
enter*
1. (Previously presented) An apparatus for selectively applying different amounts of pressure to a plurality of locations on a backside of a substantially circular semiconductor device structure, comprising:
a support structure configured to receive the semiconductor device structure;
a plurality of pressurization rings within the support structure, each of the plurality of pressurization rings being configured to apply pressure to a correspondingly annular region of the backside of the semiconductor device structure assembled with the support structure; and
a plurality of magnetic controllers, each of the plurality of magnetic controllers associated with a corresponding one of the plurality of pressurization rings.
 2. (Previously presented) The apparatus of claim 1, wherein each of the plurality of pressurization rings comprises a magnetized material.
 3. (Previously presented) The apparatus of claim 2, wherein each of the plurality of magnetic controllers is positioned adjacent the corresponding one of the plurality of pressurization rings and is oriented to repel the corresponding one of the plurality of pressurization rings.